

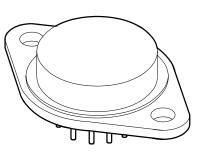
# HIGH SPEED, WIDEBAND OPERATIONAL AMPLIFIER

### M.S.KENNEDY CORP.

4707 Dey Road Liverpool, N.Y. 13088

#### FEATURES:

- Stable at Low Gain
- Fast Slew Rate 1200V/µs Typical
- Gain Bandwidth Product 1200 MHz Typical
- + Low Quiescent Current  $\pm$  14.0 mA Typical
- Low Offset 2 mV Maximum
- Drop In Replacement for OPA 3554 and TP 3554
- High Output Current ±100mA Minimum

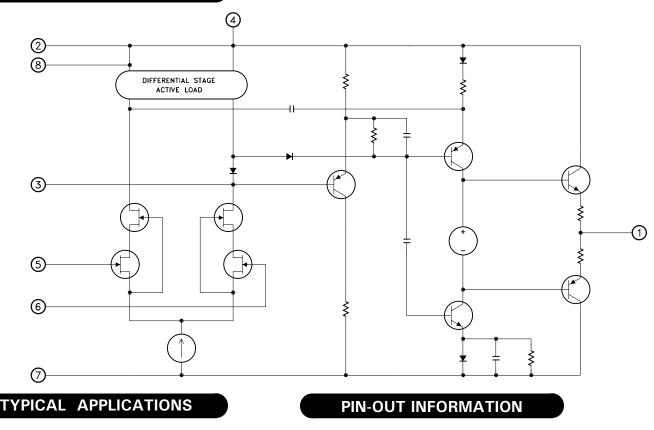


MIL-PRF-38534 QUALIFIED

#### **DESCRIPTION:**

The MSK 3554 is a pin compatible, low gain stable, drop-in replacement for the OPA 3554 and TP 3554. The MSK 3554 does not exhibit high frequency output oscillations like other versions of the 3554 when operated at closed loop gains of less than 55 V/V. The extremely low input bias current and input offset voltage ratings coupled with a high slew rate and wide bandwidth make the MSK 3554 an excellent choice for fast D/A converters, buffers, pulse amplifiers and other high speed op-amp applications. The MSK 3554 is packaged in an 8-pin TO-3 using thick film hybrid technology to obtain high reliability and compact size.

### EQUIVALENT SCHEMATIC



- Fast D/A Converters
- Pulse Amplifiers
- Video Instrumentation
- Fast Buffer/Follower
- Video Frequency Filters

- 1 Output
- 2 Positive Power Supply
- 3 Compensation
- 4 Balance

- 8 Balance
- 7 Negative Power Supply
- 6 Non-Inverting Input
- 5 Inverting Input

(315) 701-6751

### **ABSOLUTE MAXIMUM RATINGS**

$\pm V$ cc	Supply Voltage
Ιουτ	Peak Output Current ± 150mA
Vin	Differential Input Voltage
Tc	Case Operating Temperature
	MSK 3554B55°C to +125°C
	MSK 355440°C to +85°C

Ts⊤	Storage Temperature Range	-65°C to +150°C
TLD	Lead Temperature Range	300°C
	(10 Seconds)	
PD	Power Dissipation	See Curve
ТJ	Junction Temperature	175°C

### **ELECTRICAL SPECIFICATIONS**

Parameter	Test Conditions	Group A	MSK 3554B		MSK 3554				
Faranieter	Test conditions	Subgroup	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
STATIC									
Supply Voltage Range ③		-	±12	±15	±18	±12	±15	±18	V
Quiescent Current	VIN=OV	1	-	±14	±20	-	±14	±20	mA
	Av = -1v/v	2,3	-	-	±30	-	-	-	mA
Thermal Resistance ③	Junction to Case Output Devices	-	-	37	-	-	37	-	°C/W
NPUT									
Input Offset Voltage	Bal.Pins = N/C VIN = 0V Av = $-10v/v$	1	-	±0.5	±2.0	-	±0.5	±3.0	mV
Input Offset Voltage Drift	VIN=OV	2,3	-	±20	±50	-	±20	-	µV/°C
Input Offset Adjust ③	Input Offset Adjust (3) RPOT = $20K\Omega$ To + Vcc Av = $-1v/v$		Adjust to Zero		Adjust to Zero			mV	
Input Bias Current 🕦	Vcm=0V Either Input	1	-	±10	±50	-	±20	±100	pА
		2,3	-	±10	±50	-	-	-	nA
Input Offset Current	Vcm=0V	1	-	±2.0	±25	-	±2.0	±30	pА
		2,3	-	±2.0	±30	-	-	-	nA
Input Impedance ③	F = DC Differential	-	-	10 <sup>11</sup>	-	-	10 <sup>11</sup>	-	Ω
Power Supply Rejection Ratio	$(3) \qquad \Delta \text{ Vcc} = 10 \text{ V}$	-	80	110	-	80	110	-	dB
Input Noise Density ③	F = 1KHz	-	-	15	-	-	15	-	nV√Hz
Input Noise Voltage ③	F=10Hz To 1MHz	-	-	10.0	-	-	10.0	-	<i>µ</i> Vrms
OUTPUT									
Output Voltage Swing	$RL = 100\Omega$	4	±10.5	±12	-	±10	±12	-	V
Output Current	TJ < 150°C	4	±100	±120	-	±100	±120	-	mA
Settling Time ② ③	0.1% 10V step	4	-	120	150	-	120	150	nS
Power Bandwidth ③	$R_L = 100\Omega$ Vo = $\pm 10V$ Cc = 0	4	16	19	-	15	19	-	MHz
Bandwidth (Small Signal) ③	Cc = 0	4	70	90	-	70	90	-	MHz
TRANSFER CHARACTERISTICS									
Slew Rate	$V_{OUT} = \pm 10V \text{ RL} = 100\Omega \text{ Cc} = 0$	4	800	1200	-	750	1200	-	V/µS
Open Loop Voltage Gain ③ C	$C = 0$ RL = 100 $\Omega$ F = 1KHz Vout = ±10V	4	90	96	-	88	96	-	dB

#### NOTES:

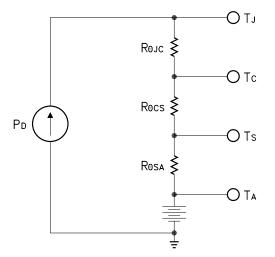
- IVUTES:
  (1) Unless otherwise specified ±Vcc = ±15Vbc
  (2) AV = -1, measured in false summing junction circuit.
  (3) Devices shall be capable of meeting the parameter, but need not be tested. Typical parameters are for reference only.
  (4) Industrial grade devices shall be tested to subgroups 1 and 4 unless otherwise specified.
  (5) Military grade devices ('B' suffix) shall be 100% tested to subgroups 1,2,3 and 4.
  (6) Subgroup 5 and 6 testing available upon request.
  (7) Subgroup 1,4 TA=Tc = +25°C
  (8) Subgroup 2,5 TA=Tc = +125°C
  (9) Subgroup 3,6 TA=Tc = -55°C
  (10) Measurement taken .5 second after application of power using automatic test equipment.

10 Measurement taken .5 second after application of power using automatic test equipment.

#### HEAT SINKING

Refer to the following thermal model and governing equations to determine appropriate heat sinking for your application.

#### Thermal Model:



#### Governing Equation:

 $T_J = P_D x (R_{\theta JC} + R_{\theta CS} + R_{\theta SA}) + T_A$ 

#### Where

- $T_J = Junction Temperature$
- PD = Total Power Dissipation
- $R_{\theta JC}$  = Junction to Case Thermal Resistance
- $R_{\theta CS}$  = Case to Heat Sink Thermal Resistance
- $R_{\theta SA}$  = Heat Sink to Ambient Thermal Resistance
- Tc = Case Temperature
- TA = Ambient Temperature
- Ts = Sink Temperature

#### Example:

This example demonstrates a worst case analysis for the opamp output stage. This occurs when the output voltage is 1/2 the power supply voltage. Under this condition, maximum power transfer occurs and the output is under maximum stress.

#### Conditions:

 $\label{eq:Vcc} \begin{array}{l} Vcc = \pm 16 VDC \\ Vo = \pm 8 Vp \mbox{ Sine Wave, Freq.} = 1 KHZ \\ RL = 100 \Omega \end{array}$ 

For a worst case analysis we will treat the +8Vp sine wave as an 8 VDC output voltage.

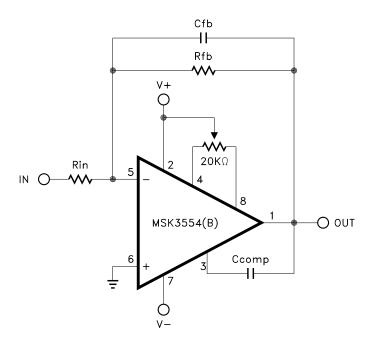
- 1.) Find Driver Power Dissipation
  - PD = (Vcc-Vo) (Vo/RL)
    - = (16V-8V) (8V/100 $\Omega$ )
    - = .64W
- 2.) For conservative design, set  $T_J = +125 \,^{\circ}C$
- 3.) For this example, worst case  $TA = +90^{\circ}C$
- 4.) R<sub> $\theta$ JC</sub> = 37°C/W from MSK 3554B Data Sheet
- 5.)  $R_{\theta}CS = 0.15^{\circ}C/W$  for most thermal greases
- 6.) Rearrange governing equation to solve for R0SA

$$\begin{array}{l} \mathsf{R}_{0}\mathsf{SA} \ = \ ((\mathsf{TJ} - \mathsf{TA})/\mathsf{PD}) \ - \ (\mathsf{R}_{0}\mathsf{JC}) \ - \ (\mathsf{R}_{0}\mathsf{CS}) \\ = \ ((125\,^\circ\mathsf{C} - 90\,^\circ\mathsf{C}) \ / \ .64\mathsf{W}) \ - \ 37\,^\circ\mathsf{C}/\mathsf{W} \ - \ .15\,^\circ\mathsf{C}/\mathsf{W} \\ = \ 54.7 \ - \ 37.15 \\ = \ 17.54\,^\circ\mathsf{C}/\mathsf{W} \end{array}$$

The heat sink in this example must have a thermal resistance of no more than 17.54 °C/W to maintain a junction temperature of no more than +125 °C.

#### **OFFSET NULL**

Typically, the MSK 3554(B) has an input offset voltage of less than  $\pm 0.5 \text{mV}$ . If it is desirable to adjust the offset closer to "zero", or to a value other than "zero", the circuit below is recommended. Rp should be a ten-turn 20K $\Omega$  potentiometer. Typical offset adjust is  $\pm 20 \text{mV}$ .

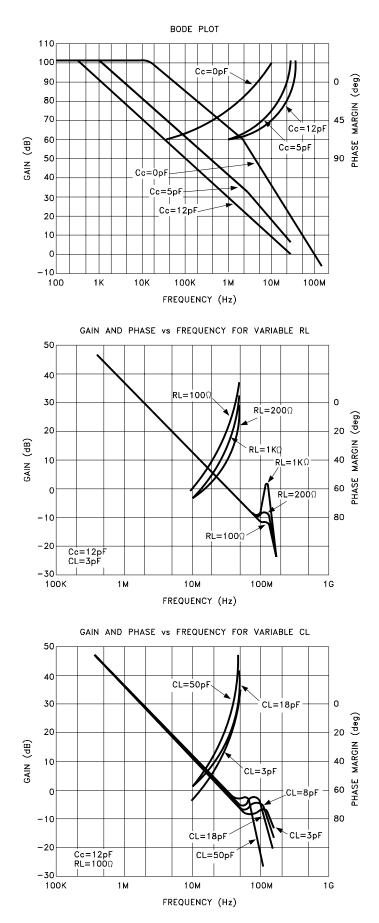


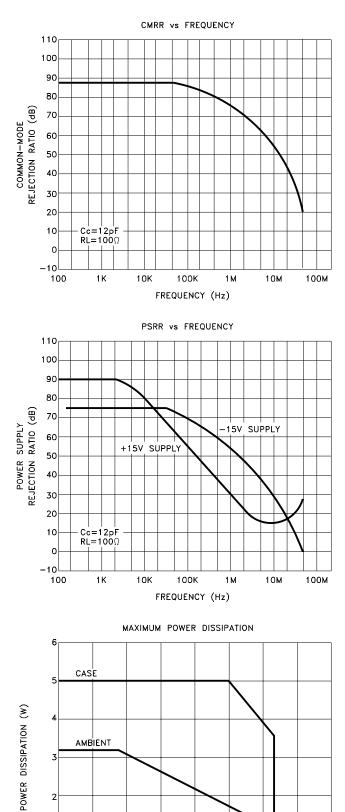
#### COMPENSATION

The compensation capacitor is connected between pins 1 and 3 and is used to optimize bandwidth and slew rate while maintaining circuit stability. The effect of compensation capacitance can be seen in the Bode Plot under the Typical Performance Curves. As closed loop gain increases, compensation capacitance can decrease and higher slew rates and wider bandwidths will be realized. See the component selection table for recommended values of input and feedback resistance as well as feedback capacitance and compensation capacitance.

COMPONENT SELECTION TABLE					
GAIN	Rin	Rfb Cfb Cc		Ccomp	
-1	5.6KΩ	5.6KΩ	2.0pF	10pF	
-10	560Ω	5.6KΩ	1.2pF	10pF	
-100	100Ω	10KΩ	0.0pF	0.0pF	
follower	0Ω	0Ω	OpF	12pF	

#### **TYPICAL PERFORMANCE CURVES**

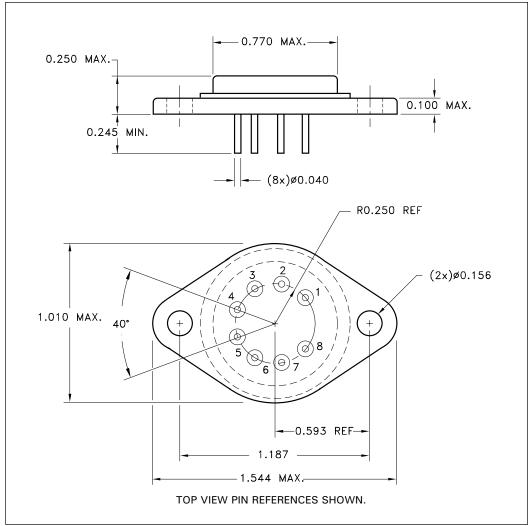




Rev. B 7/00

TEMPERATURE (\*C)

### MECHANICAL SPECIFICATIONS



ALL DIMENSIONS ARE  $\pm 0.010$  INCHES UNLESS OTHERWISE LABELED

## ORDERING INFORMATION

Part Number	Screening Level
MSK3554	Industrial
MSK3554B	Military-Mil-PRF-38534

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